

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (currently amended) A liquid crystal device comprising:
a pair of substrates opposed to one another via a seal member;
electrodes formed within an inside area of the seal member [[of]] on one substrate of the pair of substrates; and
[[an]] a first insulation film disposed on the electrodes,
wherein in an area outside [[area]] of the seal member [[of]] the one of the substrates comprises substrate includes a terrace protruding area that protrudes out of beyond an end portion of the other substrate, the terrace area comprising and the protruding area includes wiring lines connected to the electrode electrodes, and
wherein at least a part of the wiring lines [[is]] and a part of an area that is free of the wiring lines in the protruding area of the one substrate are coated with [[an]] a second insulation film made of the same material as the first insulation film.

2. (currently amended) The liquid crystal device according to Claim 1,
wherein the wiring lines comprise a conductive connection member electrically
connected to an integrated circuit or to a wiring member, the conductive connection
member ~~being not covered with~~ is free of the second insulation film.

3. (currently amended) The liquid crystal device according to Claim 2,
wherein the conductive connection member is connected to the integrated
circuit or to the wiring member via an anisotropic conductive film, and
wherein an edge of the anisotropic conductive film ~~overlaps~~ is formed on the
second insulation film.

4. (currently amended) A method for manufacturing a liquid crystal device having a pair of substrates opposed to one another via a seal member, one substrate of the pair of substrates comprising including a terrace protruding area protruding out of beyond an end portion of the other substrate, the method comprising the steps of:

forming electrodes on the one substrate of the pair of substrates[[,]] and wiring lines connected to the electrode electrodes on the terrace protruding area; and

forming an insulation film covering at least a part of the electrodes and the wiring lines and a part of an area that is free of the wiring lines in the protruding area of the one substrate.

5. (previously presented) The method for manufacturing a liquid crystal device according to Claim 4,

wherein the wiring lines comprise a conductive connection member electrically connected to an integrated circuit or to a wiring member, the conductive connection member being free from the insulation film.

6. (original) The method for manufacturing a liquid crystal device according to Claim 5,

wherein the conductive connection member is connected to the integrated circuit or to the wiring member via an anisotropic conductive film, and

wherein an edge of the anisotropic conductive film overlaps the insulation film.

7. (currently amended) The method for manufacturing a liquid crystal device according to Claim 6,

~~wherein a positioning mark is formed on the one of the substrates,~~

wherein an edge of the insulation film is formed along one edge of [[the]] a first positioning mark, and

wherein the edge of the anisotropic conductive film is formed along another one edge of [[the]] a second positioning mark.

8. (currently amended) A liquid crystal device comprising:

a pair of substrates opposed to one another via a seal member;

electrodes formed within an inside area of the seal member [[of]] on one substrate of the pair of substrates;

an overcoat layer formed on the electrodes; and

~~the overcoat layer~~ an orientation film formed on the overcoat layer,

wherein the in an area outside [[area]] of the seal member [[of]] the one of the substrates comprises a terrace area substrate includes a protruding area out of beyond an end portion of the other substrate that has two corners formed on the one substrate in plan view, the terrace area the protruding area including wiring lines connected to the electrodes~~[[,]]~~ and the wiring lines including the covered with the overcoat layer and the orientation film formed thereon, and

wherein at least a part of the wiring lines and at least one of the corners of the protruding area are coated with a protective film including the overcoat layer and the orientation film,

and

wherein the entire overcoat layer is covered with the orientation film on the terrace protruding area.

9. (currently amended) A method for manufacturing a liquid crystal device having a pair of substrates opposed to one another via a seal member, one substrate of the pair of substrates comprising a terrace including a protruding area protruding out of beyond an end portion of the other substrate, the method comprising the steps of:

forming electrodes on one substrate of the pair of substrates[[,]] and wiring lines connected to the electrode electrodes on the terrace protruding area which has two corners formed on the one substrate in plan view;

forming an overcoat layer on the electrodes, and on the wiring lines, and at least one of the corners of the protruding area;

forming an orientation film on the overcoat layer; and

applying a rubbing treatment to the orientation film,

wherein the entire overcoat layer is covered with the orientation film on the terrace protruding area.

10. (currently amended) A liquid crystal device comprising:

a pair of substrates opposed to one another via a seal member;

electrodes formed within an inside area of the seal member [[of]] on the pair of substrates; and

an insulation layer formed on the electrodes of one substrate of the pair of substrates,

wherein in an area outside [[area]] of the seal member [[of]] the one of the substrates comprises substrate includes a terrace protruding area protruding out of beyond an end portion of the other substrate;

wherein the terrace protruding area includes wiring lines electrically connected to the electrodes provided on the other substrate via a conductive connection member in the seal member, at least a part of the wiring lines being coated with the insulation layer, and

wherein the wiring lines immediately beneath the conductive connection member are free of the insulation layer ~~is formed on the area except the sites corresponding to the conductive connection member.~~

11. (currently amended) The liquid crystal device according to Claim 10, wherein the insulation layer comprises at least either [[the]] an overcoat layer covering the electrode electrodes, or [[the]] an orientation film formed above the electrode electrodes.

12. (currently amended) A liquid crystal device comprising:

a pair of substrates opposed to one another via a seal member;

electrodes formed within an inner area of the seal member [[of]] on one substrate of the pair of substrates; and

an insulation film formed on the electrodes,

wherein in an area outside [[area]] of the seal member [[of]] the one of the substrates comprises substrate includes a terrace protruding area protruding out of beyond an end portion of the other substrate[[;]] , the terrace protruding area comprises including a packaging area in which wiring lines connected to the electrodes and to an outer circuit including [[ICs]] an IC for addressing the liquid crystal device are packaged[[;]] , at least a part of the wiring lines are coated with an insulating film made of the same material as the insulation film[[;]] formed on the electrodes , and a mold member is disposed on the wiring lines formed between the packaging area and the seal member, the entirety of the mold member being disposed between the seal member and the IC.

13. (withdrawn) A method for manufacturing a liquid crystal device comprising a pair of substrates opposed to one another via a seal member, one of the pair of substrates comprising a terrace area protruding out of an end portion of the other substrate, comprising the steps of:

forming electrodes on one of the pair of the substrates, and wiring lines connected to the electrode on the terrace area;

forming an insulation film covering at least a part of the electrodes and the wiring lines;

adhering one of the substrates to the other substrate;

inspecting a turn-on function of the liquid crystal device using the wiring lines; and

molding the wiring lines in an area used for the turning-on inspection.

14. (currently amended) A liquid crystal device comprising:
a pair of substrates opposed to one another via a seal member; and
an orientation film provided at an inner face side of one substrate of the pair of substrates,

wherein in an area [[the]] outside area of the seal member [[of]] the one of the substrates ~~comprises~~ substrate includes a terrace protruding area protruding out of the end portion of the other substrate, the terrace area comprising including wiring lines pulled extending out of an inside area of the seal member[[; and]] .

wherein at least a part of the wiring lines is covered with an insulation film,
at least an edge of the insulation film being covered with the orientation film[[.]]
and

wherein the protruding area includes a positioning mark, the positioning mark defines both positions of the edge of the insulation film and an edge of the orientation film.

15. (currently amended) The liquid crystal device according to Claim 14,
wherein [[the]] in an area inside [[area]] of the seal member [[of]] the one of the substrates ~~comprises~~ substrate includes electrodes for applying an electric field to the liquid crystal, the orientation film being provided on the electrode electrodes, and
wherein a protective film is provided between the electrodes and the orientation film, the protective film being made of [[the]] a same material as the insulation film.

16. (original) The liquid crystal device according to Claim 14,
wherein the orientation film is formed so as to cover the entire insulation film.

17. (currently amended) The liquid crystal device according to Claim 14,
~~wherein the terrace area comprises a positioning mark, the positioning mark~~
includes two outer edges, the insulation film is formed along one outer edge of the
positioning mark, and the orientation film is formed along another outer edge of the
positioning mark.

18. (currently amended) The liquid crystal device according to Claim 17,
wherein ~~the one of the outer edges~~ edge is formed to be opposite [[to]] the ~~other~~
another outer edge.

19. (currently amended) The liquid crystal device according to Claim [[17]]
14,
wherein the positioning mark is made of the same material as the wiring lines.

20. (currently amended) A method for manufacturing a liquid crystal device having a pair of substrates opposed to one another via a seal member, one substrate of the pair of substrates comprising including a terrace protruding area protruding out of beyond an end portion of the other substrate, the method comprising the steps of:

forming electrodes on the one of the pair of substrates, substrate and wiring lines connected to the electrode electrodes on the terrace protruding area;

forming an insulation film covering at least a part of the electrodes and the wiring lines[, and] :

forming an orientation film on the insulation film[,] ; and

forming a positioning mark on the one substrate,

wherein the insulation film is formed along one outer edge of the positioning mark, the orientation film is formed along another outer edge of the positioning mark, and

wherein an edge of the insulation film is covered with the orientation film on the terrace protruding area.

21. (cancelled)

22. (new) The liquid crystal device according to Claim 1,
wherein the protruding area includes a packaging area in which wiring lines
connected to the electrodes and to an outer circuit including an IC for addressing the
liquid crystal device are packaged, and

wherein the packaging area is free of the second insulation film.

23. (new) The liquid crystal device according to Claim 2,
wherein terminals connected to the integrated circuit are formed on the
protruding area, and

the terminals are free of the second insulation film.

24. (new) The liquid crystal device according to Claim 3,
wherein the insulation film is formed along one edge of a first positioning mark,
and

wherein the anisotropic conductive film is formed along one edge of a second
positioning mark.

AMENDMENTS TO THE DRAWINGS

The attached 27 "Replacement Sheets" of drawings include changes to Figure 20 to correct the reference indicia of the components of the insulation layer 110 from "110(111.112)" to "110(112.113)" and to Figures 31a-b to indicate that these two Figures are depictions of the prior art. Support for the correction to Figure 20 can be found at least on Page 73, lines 16-20. Please replace the original 27 sheets of drawings with the attached 27 "Replacement Sheets" of drawings.

Attachment: 27 Replacement Sheets